Product Change Notification

Change Notification #:	**118696-01**
Change Title:	**Select Hot Swap Backplane F2U8X25S3PHS and F1U8X25S3PHS,** **PCN 118696-01, Product Design,** **HSBP interposer implementation** **Reason for Revision: Updating description of change and Products Affected table**
Date of Publication:	**December 8, 2021**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	December 18, 2021

* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

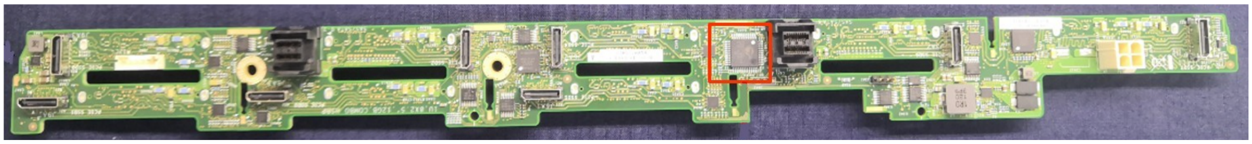
Reason for Revision: Updating description of change and Products Affected table

Due to Integrated Circuit (IC) shortage from the supplier, a Programmable System-On-Chip (PSOC) used on the F2U8X25S3PHS and F1U8X25S3PHS Hot Swap Backplanes needs to be replaced with an alternative component. The new component is identical in function than previous one but differs in form factor. For business continuity, demand fulfillment and to minimize customer impact, an interposer PCB supporting the new component was used. The new component has passed all functional and electrical validation test successfully.

For such reason, products listed in the “Products Affected” table could be delivered to customers with any of two different PBA codes of hot swap backplanes which can be identified as:

MM#: 955868 - H88382-351 or H88382-352

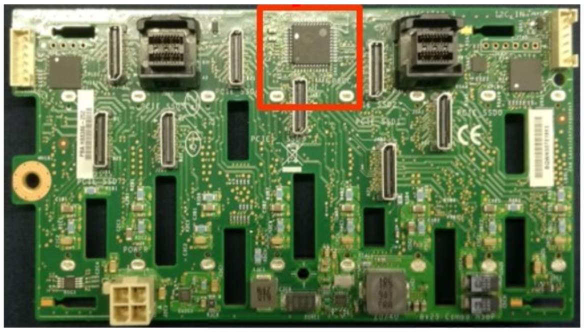
PBA Code Before - H88382-351



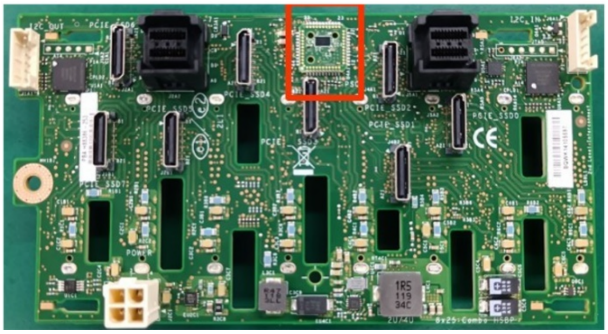
PBA Code After - H88382-352

MM#: 955870 - H88386-252 or H88386-253

PBA Code Before - H88386-252



PBA Code After - H88386-253



Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Please contact your local Intel Field Sales Rep if you have any further questions about these changes

Products Affected/Intel Ordering Codes:

Marketing Name	**Product Code**	**MM#**	**Pre Change TA**	**Post Change TA**	**Backplane PBA**
1U 8x2.5 inch SAS/NVMe Hot Swap Backplane F1U8X25S3PHS, Single	F1U8X25S3PHS	955868	J11107-006	J11107-007	H88382-351 H88382-352
2U 8x2.5inch SAS/NVMe Hot Swap Backplane F2U8X25S3PHS, Single	F2U8X25S3PHS	955870	H97230-005	H97230-006	H88386-252 H88386-253

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
December 03, 2021	00	Originally Published PCN
December 08, 2021	01	Updating description of change and Products Affected table

Product Change Notification
118696-01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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